

Switching Diode

FEATURES

- Fast switching speed
- Surface device type mounting
- Moisture sensitivity level 1
- High conductance power dissipation
- For general purpose switching applications
- Pb free version and RoHS compliant
- Packing code with suffix "G" means green compound (halogen-free)

MECHANICAL DATA

- Case: SOT-363 small outline plastic package
- Terminal: Matte tin plated, lead free., solderable per MIL-STD-202, Method 208 guaranteed
- High temperature soldering guaranteed : 260°C/10s



MAXIMUM RATINGS AND ELECTR	ICAL CHARACTERIST	ΓICS (T _A =25°	°C unless otherwise noted)	
PARAMETER		SYMBOL	VALUE	UNIT
Power Dissipation		P_{D}	200	mW
Repetitive Peak Reverse Voltage		V_{RRM}	80	V
Reverse Voltage		V_R	57	V
Average Rectified Forward Current		$I_{F(AV)}$	500	mA
Average Rectified Output Current		I _o	250	mA
Non-Repetitive Peak Forward Surge Current	@t = 1 µs @t = 1 s	I _{FSM}	4 1.5	А
Thermal Resistance (Junction to Ambient)		$R_{\theta JA}$	625	°C/W
Junction and Storage Temperature Range		T_J , T_STG	-55 to 150	°C

P.	ARAMETER	SYMBOL	MIN	MAX	UNIT
Reverse Breakdown Voltage	I _R =100μA	V _(BR)	80	-	V
	I _F =5.0mA	7	0.620	0.715	
Forward Voltage	I _F =10mA	V _F	-	0.855	\Box v
	I _F =100mA	V _F	-	1.000	☐
	I _F =150mA		-	1.250	
Reverse Leakage Current	V _R =70V		-	100	nA
	V_R =75 V , T_J =150 $^{\circ}$ C	V_{F}	-	50	μA
	$V_{R}=25V$, $T_{J}=150^{\circ}C$	V _F	-	30	μA
	V _R =20V		-	25	nA
Junction Capacitance	V _R =6V, f=1MHz	C _J	-	3.5	pF
Reverse Recovery Time	I _F =5mA, V _R =6V	t _{rr}	-	4.0	ns

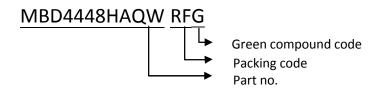
Note 1: Device mounted on FR-4 PCB, 1 inch × 0.85 inch × 0.062 inch

Note 2: Short duration test pulse uesd tu minimize self-heating effect

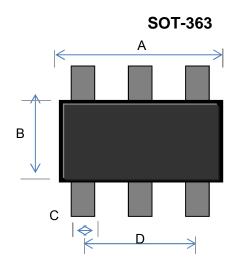
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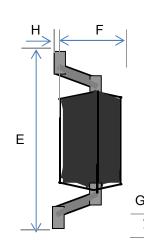


ORDER INFORMATION (EXAMPLE)



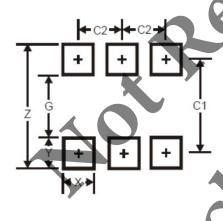
DIMENSIONS





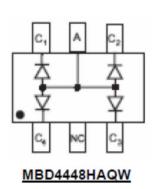
DIM. Un		(mm)	Unit (inch)	
	Min	Max	Min	Max
Α	2.00	2.20	0.079	0.087
В	1.15	1.35	0.045	0.053
С	0.15	0.35	0.006	0.014
D	1.20	1.40	0.047	0.055
E	2.15	2.45	0.085	0.096
F	0.85	1.05	0.033	0.041
G	0.25	0.46	0.010	0.018
I	0.00	0.10	0.000	0.004

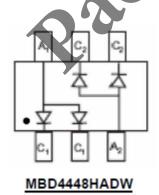
SUGGESTED PAD LAYOUT

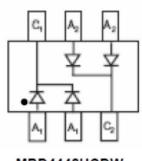


DIM.	Unit (mm)	Unit (inch)	
Dilvi.	Тур.	Тур.	
Z	3.20	0.126	
G	1.60	0.063	
Х	0.55	0.022	
Υ	0.80	0.031	
C1	2.40	0.094	
C2	0.95	0.037	

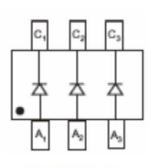
PIN CONFIGURATION







MBD4448HSDW



MBD4448HCDW

MBD4448HTW



MARKING

Part no.	Marking code
MBD4448HAQW	KA5
MBD4448HADW	KA6
MBD4448HCDW	KA7
MBD4448HSDW	KA8
MBD4448HTW	KAA

Aot Recommended code. Rhinks

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